

# ULTRA HDI CAPABILITIES

Parameter	Minimum (Micron)	Comments
Line width	15 (+/-5%)	Tolerance applies to trace widths up to 50 microns +/-2.5 microns for wider lines
Line space	12.5 (+/-5%)	
Line copper thickness (> 50 micron lines)	10-40 (+/-5%)	
Line copper thickness (25 micron lines)	25 max (+/-5%)	
Line copper thickness (12.5-20 micron lines)	20 max (+/-5%)	
Microvia hole diameter	75	Rigid: 50 um thick material or less
Microvia pad diameter	200	Advanced: 50 um via in 25 um flex
Through hole diameter	150	100 micron for 0.8 mm thick boards
Through hole pad diameter	300	200 micron for 100 micron hole dia. for 0.8 mm thick boards
Via Clearance to Board Edge (Laser Cut)	125	Edge of pad or trace to board edge
Via Clearance to Board Edge (Mech route)	250+	
Copper thickness in thru holes	25 nominal	
Copper thickness in microvia	25 nominal	
Copper Via Fill	Yes	
Non-Conductive Via Fill	Yes	Vias larger than 150 microns
Via-In-Pad-Plated-Over (VIPPO)	Yes	See recommendation in FAQs

